



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Michael S. Leung et al. Confirmation No. 8955
Serial No. 10/666,399 Examiner: Le, Thao X.
Filed: September 18, 2003 Art Unit: 2814
Docket No. P0298US-7

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Sir:

In response to the Office Action mailed on September 30, 2005, please amend the above-identified application as follows:

AMENDMENTS TO THE CLAIMS are reflected in A Listing of the Claims shown beginning on page 2 of this paper.

REMARKS AND ARGUMENTS begin on page 9 of this paper.